

1/5

FIG. 1A

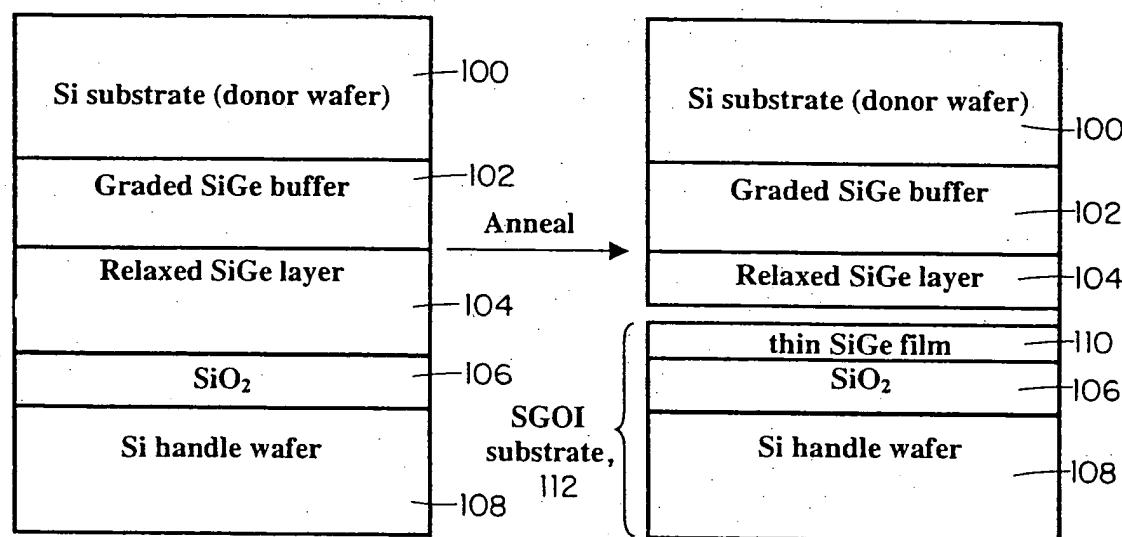
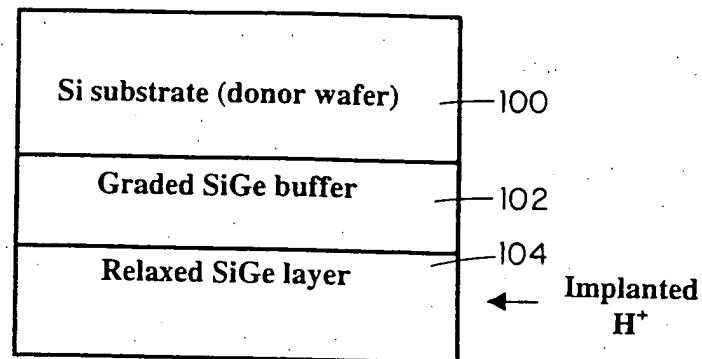
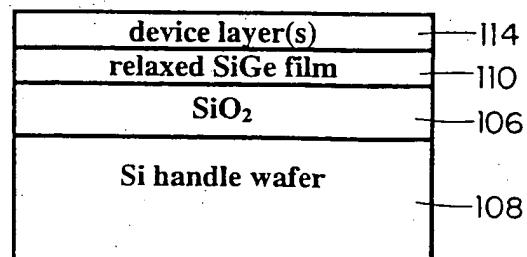


FIG. 1B

FIG. 1C



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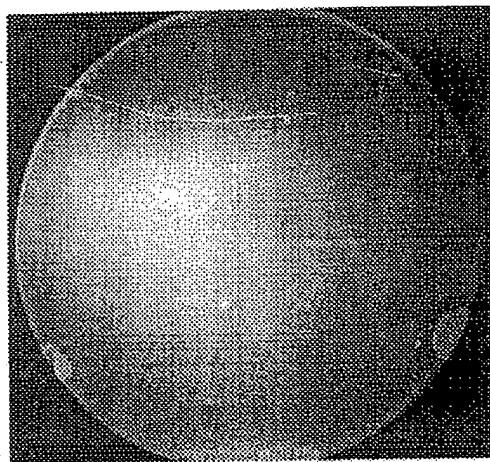


FIG. 2A

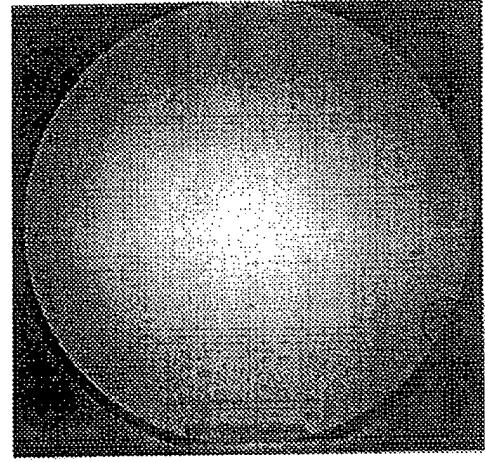


FIG. 2B

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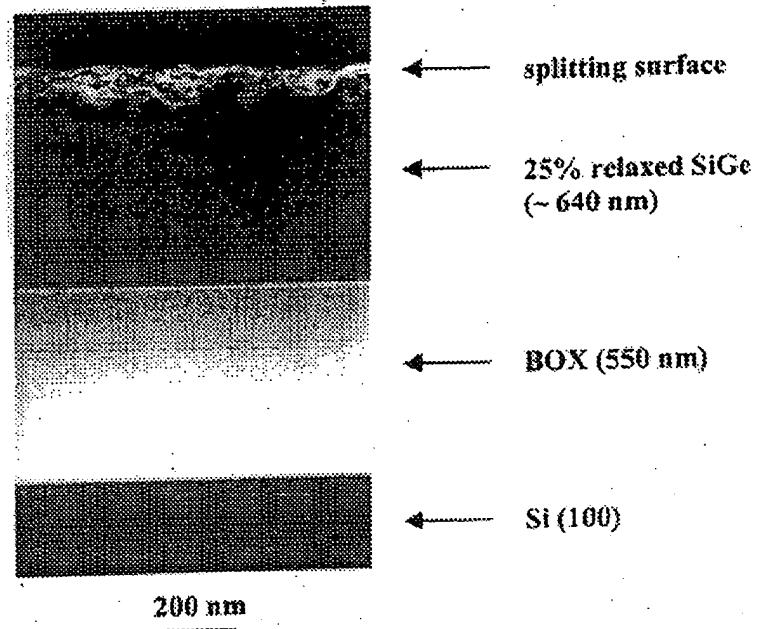


FIG. 3

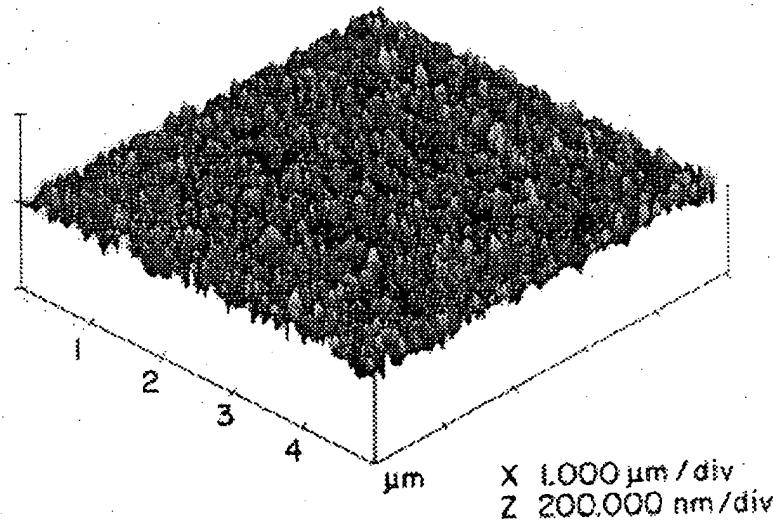


FIG. 4

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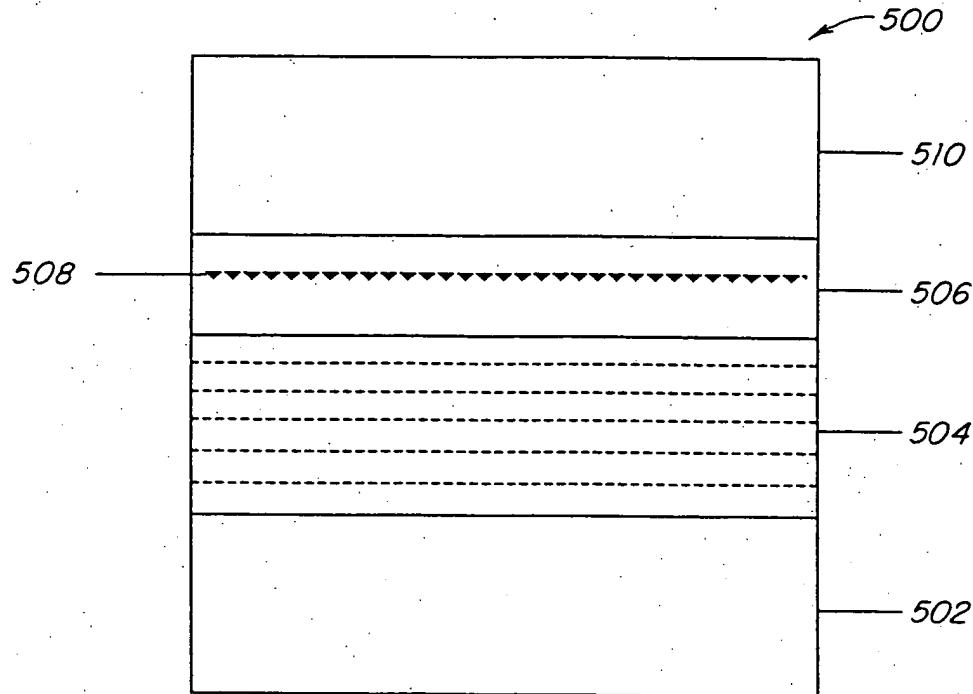


FIG. 5

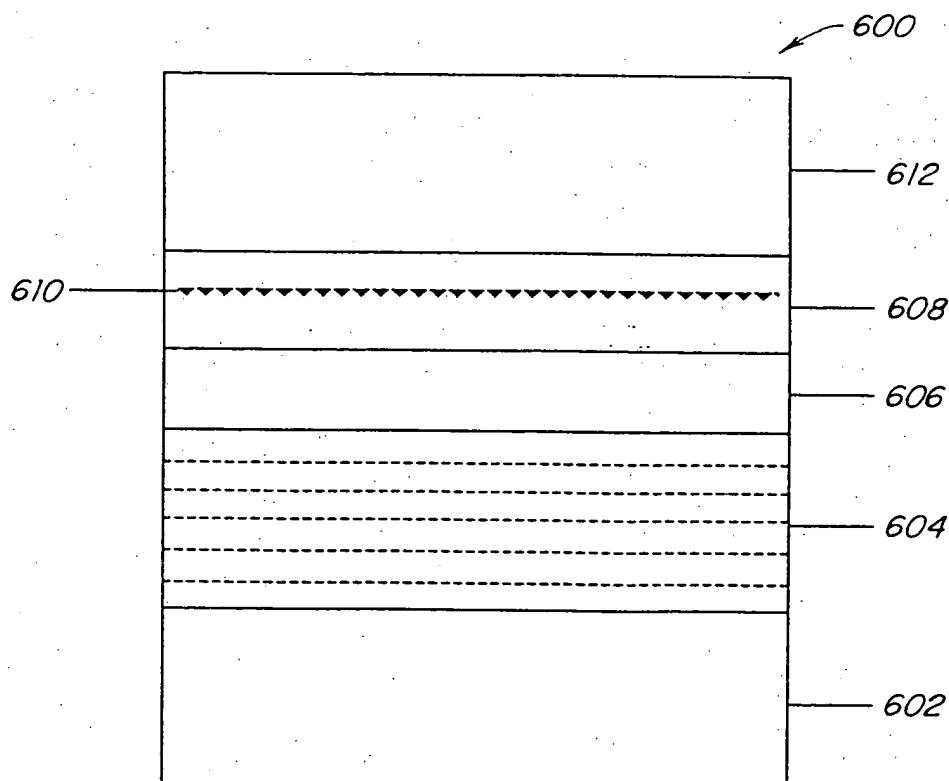


FIG. 6

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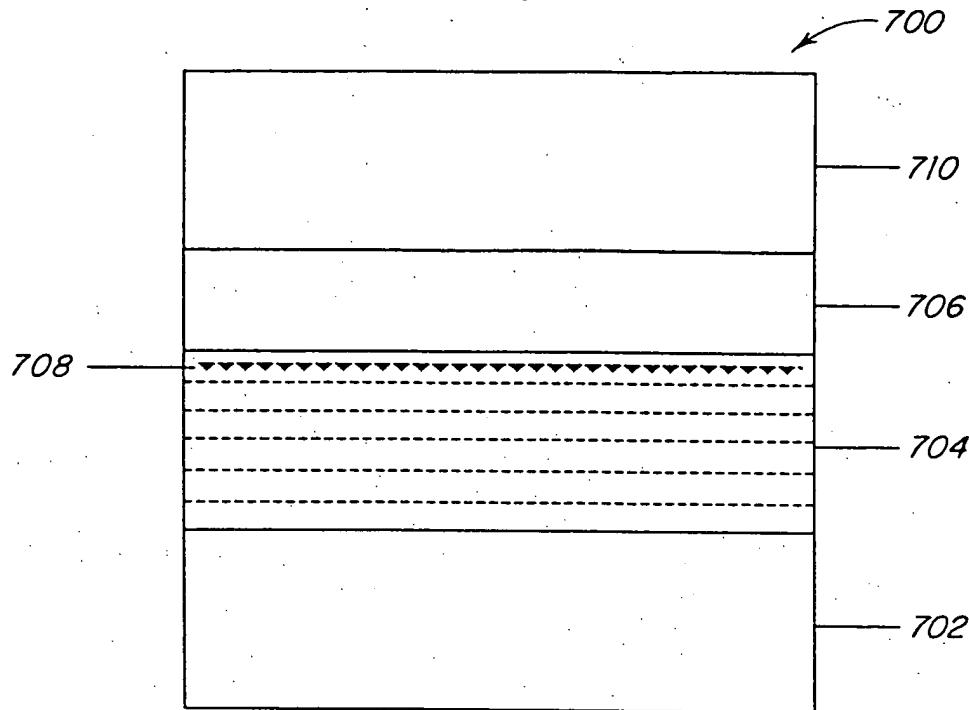


FIG. 7

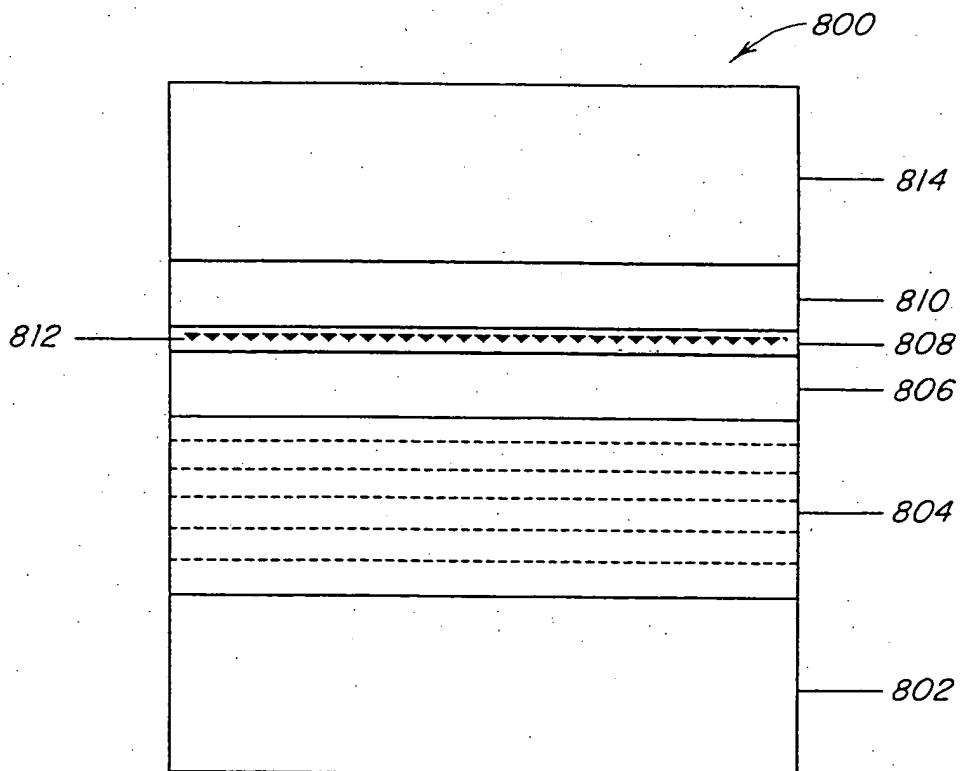


FIG. 8